ABSTRACT

A sheet peeling apparatus 50 which, after sticking a web material LS laminated with heat sensitive adhesive type adhesive sheet S on a release liner PS to a semiconductor wafer W, cuts the web material along the periphery of a semiconductor wafer and peels off a release liner PS portion positioned on the semiconductor wafer and a web material portion S1 positioned at the periphery side around the semiconductor wafer. The apparatus is equipped with a roll 135 capable of performing a relative movement with respect to the table 47 supporting the wafer W, and is arranged to stick a peeling tape ST to the web material LS with the roll, and then winds to peel off the tape; thus, only the adhesive sheet S is left on the wafer W.